

ABSTRACT OF THE DISCLOSURE

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A system that decapsulates an integrated circuit package while the package is mounted to a printed circuit board. The system includes a tray that supports a printed circuit board which has at least one integrated circuit package mounted to the board.

Mounted to the tray is a clamp which clamps an injection head to the top of the package. The injection head is coupled to a source of decapsulation fluid which is sprayed onto the package. The decapsulation fluid is circulated across the package to remove the package material and expose the underlying integrated circuit. The injection head has a gasket that is pressed onto the package to prevent the fluid from leaking onto the printed circuit board. After the plastic is decapsulated the head can be removed from the package so that the integrated circuit can be tested while the circuit is connected to the printed circuit board.